



## Material Content Data Sheet



<b>Sales Product Name</b>		BAL 74 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000550676						
<b>Package</b>		PG-SOT23-3-12		<b>Weight*</b>		8.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		11	
	noble metal	gold	7440-57-5	0.010	0.11		1125	
	inorganic material	silicon	7440-21-3	0.017	0.19	0.30	1922	3059
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		66	
	non noble metal	titanium	7440-32-6	0.003	0.03		331	
	non noble metal	chromium	7440-47-3	0.009	0.10		992	
	non noble metal	copper	7440-50-8	2.956	32.93	33.07	329254	330643
wire	noble metal	gold	7440-57-5	0.010	0.11	0.11	1121	1121
encapsulation	organic material	carbon black	1333-86-4	0.058	0.64		6408	
	plastics	brominated resin	-	0.086	0.96		9611	
	inorganic material	antimonytrioxide	1309-64-4	0.115	1.28		12815	
	plastics	epoxy resin	-	1.237	13.78		137763	
	inorganic material	silicondioxide	60676-86-0	4.256	47.42	64.08	474165	640760
leadfinish	non noble metal	tin	7440-31-5	0.150	1.67	1.67	16670	16670
plating	noble metal	silver	7440-22-4	0.070	0.77	0.77	7746	7746
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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